



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: S. Maezawa et al. : Art Unit: 2827  
Serial No.: 09/913,372 : Examiner: I. B. Patel  
Filed: November 27, 2001 :  
FOR: MULTILAYER PRINTED WIRING BOARD AND :  
ITS MANUFACTURING METHOD (AS :  
AMENDED) :

## **AMENDMENT**

Assistant Commissioner for Patents  
Washington, DC 20231

SIR:

Responsive to the Official Action dated **November 6, 2002**, please amend the above-identified application as follows:

## IN THE TITLE:

Please replace the Title with the following:

## MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD

#### IN THE DRAWINGS.

Please replace Figs. 1-3 with new Figs. 1(a)-1(d), 2(a)-2(d), and 3(a)-3(f).

#### IN THE CLAIMS:

Please cancel claims 11-17, 24-26 and 30, 35

Please replace claims 1, 18-23 and 27-29 with the following amended claims:

1. (Amended) A multilayer printed wiring board comprising:

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